



PK814 (v1.0) October 7, 2016

## 100% Material Declaration Data Sheet for RS484

Average Weight : 3.6759 g

Component	Substance Description	CAS # or Description	% of component	Use in product	Component weight / substance weight ( in grams)	Component % of total
Silicon die					<b>0.237468</b>	<b>6.460%</b>
	Silicon	NA	100	basis	0.237468	
Bump					<b>0.011261</b>	<b>0.306%</b>
	Tin	7440-31-5	63.00	basis	0.007094	
	Lead	7439-92-1	37.00	basis	0.004167	
Underfill					<b>0.035000</b>	<b>0.952%</b>
	Bisphenol F/ epichlorohydrin copolymer	9003-36-5	20.00	basis	0.007000	
	Phenolic resin	trade secret	15.00	basis	0.005250	
	Bisphenol A type liquid epoxy	25068-38-6	5.00	basis	0.001750	
	Amine type accelerator	trade secret	5.00	basis	0.001750	
	Silicon dioxide	60676-86-0	51.50	filler	0.018025	
	Carbon black	1333-86-4	1.00	color agent	0.000350	
	Additives	trade secret	2.50	additives	0.000875	
Solder ball					<b>0.222192</b>	<b>6.045%</b>
	Tin	7440-31-5	63.00	Main material	0.139981	
	Lead	7439-92-1	37.00	Main material	0.082211	
Heat sink					<b>2.190000</b>	<b>59.577%</b>
	Copper	7440-50-8	97.94	Main material	2.144886	
	Nickel	8049-31-8	2.06	Main material	0.045114	
Substrate					<b>0.980000</b>	<b>26.660%</b>
	Copper	7440-50-8	36.82		0.360836	
	Tin	7440-31-5	1.09		0.010682	
	Lead	7439-92-1	0.42		0.004116	
	Core (HL832NS)	N/A	47.89		0.469322	
	ABF (GX13)	N/A	11.25		0.110250	
	Solder Mask (SR7200G)	N/A	2.54		0.024892	

### Revision History

Date	Version	Description of Revisions
10/7/2016	1.0	Initial Xilinx release.